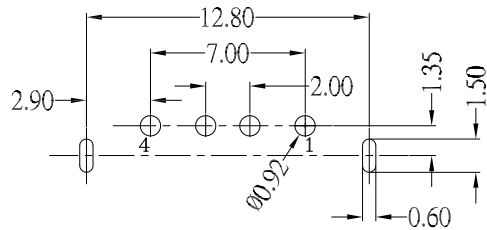
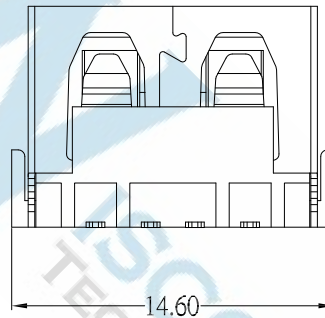
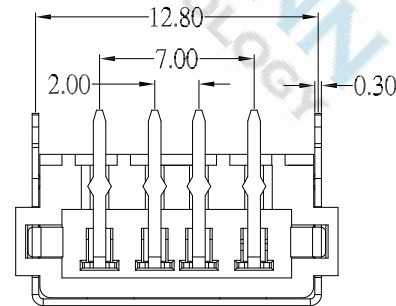


SECTION A-A



P.C.B LAYOUT MOUNTING PATTERN



SPECIFICATIONS

Electrical:

- 1.Contact Resistance: 30 mΩ Max
- 2.Dielectric Withstanding Voltage: 500 V AC
- 3.Insulation Resistance: 1,000 MΩ Min

Mechanical:

- 1.Connector Mate and Unmate Force
 - 1.1 Mate force: 3.57 kgf (Max)
 - 1.2 Unmate force: 1.02 kgf (Min)

Material:

- 1.Housing: Thermoplastic,UL 94V-0
- 2.Contact: Phosphor Bronze
- 3.Shell: Phosphor Bronze / Spcc

Finish:

- 1.Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer

DIMENSIONS TOLERANCE METRIC .0=±0.30 .00=±0.20 .000=±0.10 ANG.=±2°	單位(UNITS)	MM	處理(FINISH)	SEE NOTE	審核(CH'K)	Calvin	圖名(NAME) USB2.0 A/F短體10.0mm 正向 DIP 魚叉 H:6.85mm	WISCONN Technology Co., Ltd Tel:02-2790-1979 Fax:02-2790-1569								
	數量(QT'Y)	N/A	繪圖(DRAW)	Johnson	核准(APP'D)	Selena								料號(PART NUMBER)	WU2AF-4-xxxIR-4SS12	
	材料(MT'L)	SEE NOTE	設計(DE'N)	Mike	日期(DATE)	SEP.10.2015	圖號(DRAW NUMBER)	T002	比例(SCALE)	1/1	圖紙(SIZE)	A4	頁次(SHEET)	1	版次(REV.)	A
	圖檔(FILE NAME .DWG)															